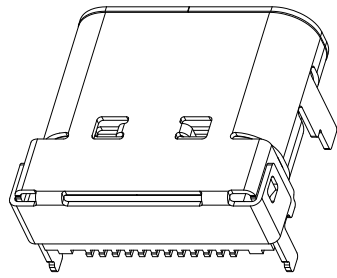
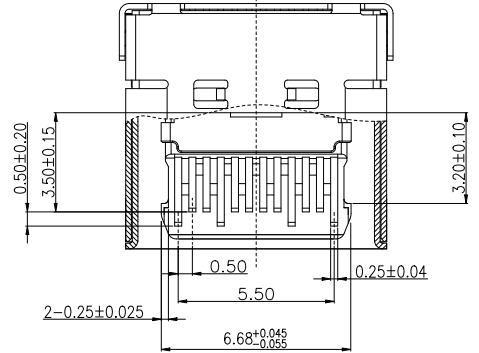


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	GZY

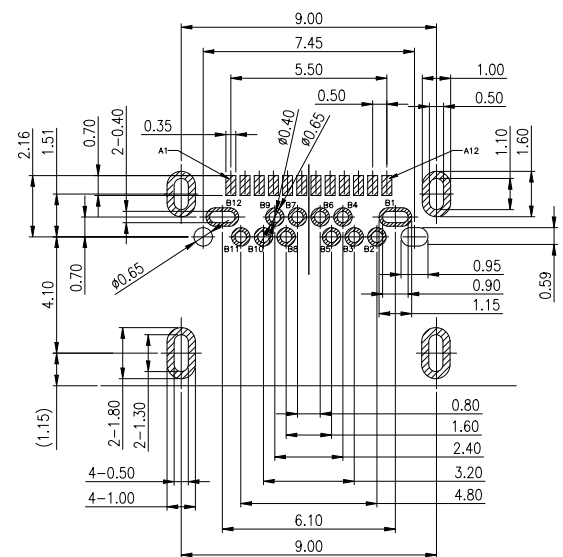
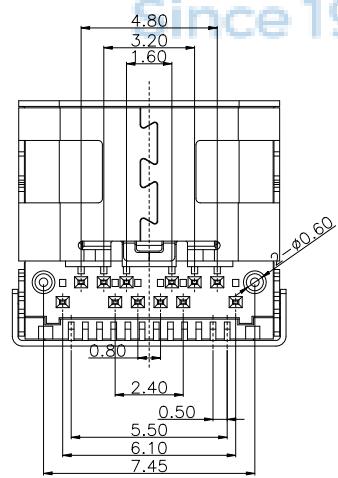
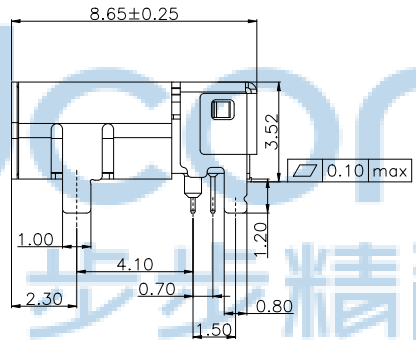
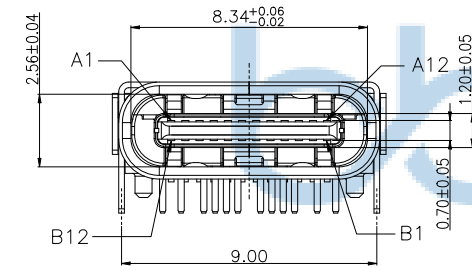


- 1.MATERIAL:**
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
PLATED GOLD ON CONTACT AREA,
G/F GOLD ON SOLDER AREA,
50u" NICKEL PLATING OVER ALL.
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
EMI SHILD: SUS304-H,T=0.12±0.03mm
LATCH: SUS301-H,T=0.15±0.03mm
- 2.MECHANICAL:**
INSERTION: 5~20N.
EXTRACTION: 8~20N.
DURABILITY: 10000 CYCLES
- 3.ELECTRICAL:**
CURRENT: 5A MAX FOR VBUS;
1.25A FOR GND, 0.25A FOR OTHER OTHER.
VOLTAGE: 20VDC MAX
WITHSTANDING VOLTAGE: 100V AC.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
- 4.ENVIRONMENTAL**
TEMPERATURE RANGE: -30°C TO +80°C



USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	B11	SSRxp1	Positive half of first SuperSpeed RX differential pair
A3	SSTxm1	Negative half of first SuperSpeed TX differential pair	B10	SSRxm1	Negative half of first SuperSpeed RX differential pair
A4	Vbus	Bus Power	B9	Vbus	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	dm2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dm1	Negative half of the USB 2.0 differential pair-Position 1	B6	hp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	Vbus	Bus Power	B4	Vbus	Bus Power
A10	SSRxq2	Negative half of second SuperSpeed RX differential pair	B3	SSTx2	Negative half of second SuperSpeed TX differential pair
A11	SSRxq2	Positive half of second SuperSpeed RX differential pair	B2	SSTx2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return



RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05

6	EMA	SUS 304		
5	MID-PLATE	SUS 301		
4	CONTACT DIP	C7025		GOLD/TIN PLATED
3	CONTACT SMT	C7025		GOLD/TIN PLATED
2	SHELL	SUS 304		NI PLATED
1	HOUSING	LCP	BLACK	UL 94V-0
NO:	DESCRIPTION	MATERIAL	COLOR	REMARK

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深圳市步步精科技有限公司

NAME: TYPE-C 母座 24P 板上型 双壳 外壳四脚DIP 端子DIP+SMT
L=8.65 外壳脚长1.2 带柱 不锈钢外壳 LCP黑胶 编带

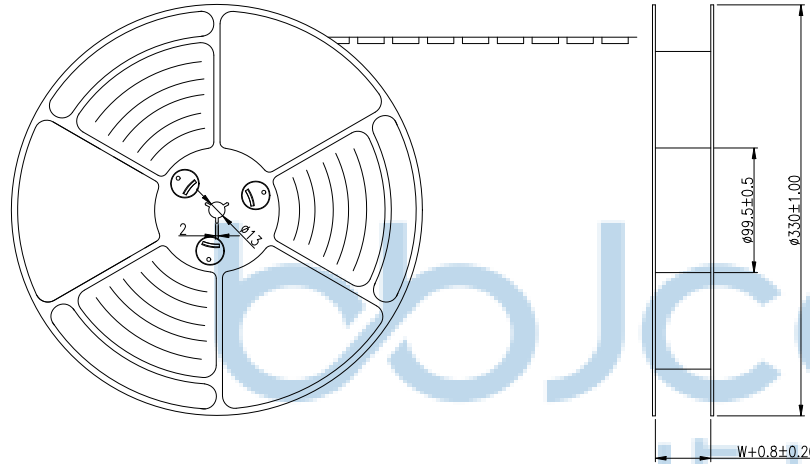
APPD. JM_Zheng
CHKD. LYX
DR. GZY

PJ. NO.:
SIZE: A4 DRW NO.:
FINISH: SEE NOTES MAT'L.: SEE NOTES
SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	GZY

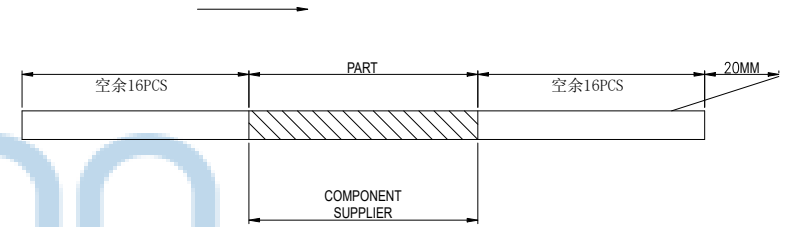


出料方向
PULL OUT DIRECTEON



NOTES

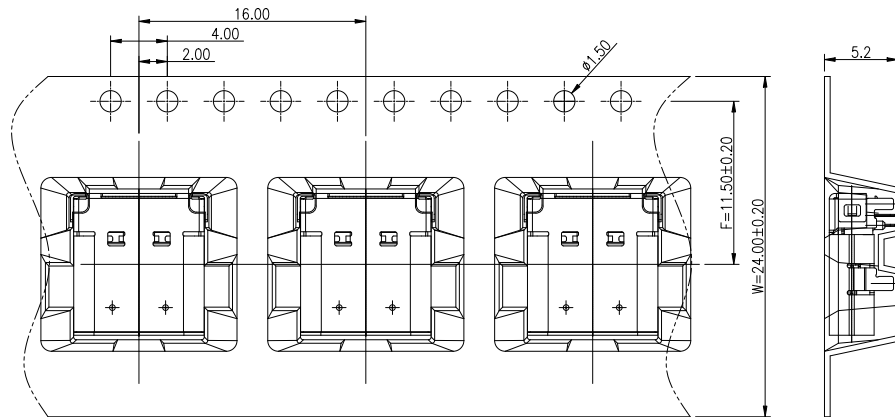
- 帶子引導長度
LEAD TAPE LENGTH
出料方向
PULL OUT DIRECTEON



- 出貨'運輸過程中一定注意:
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT:
卷帶在運輸過程中不能散開
PEELING OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION

Since 1987

步步精科技

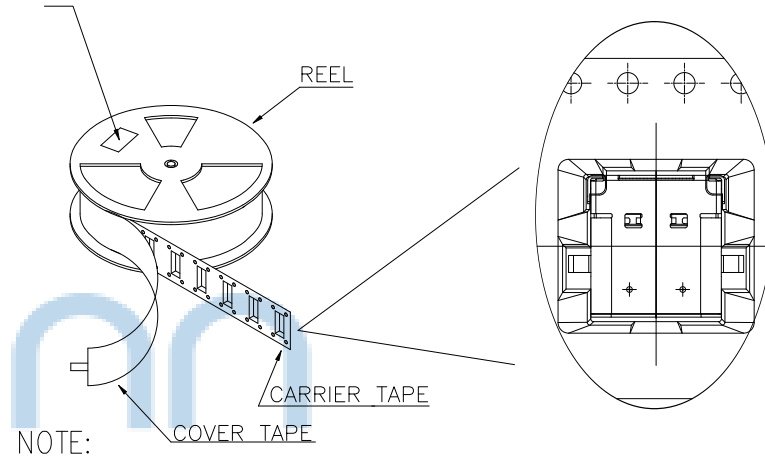
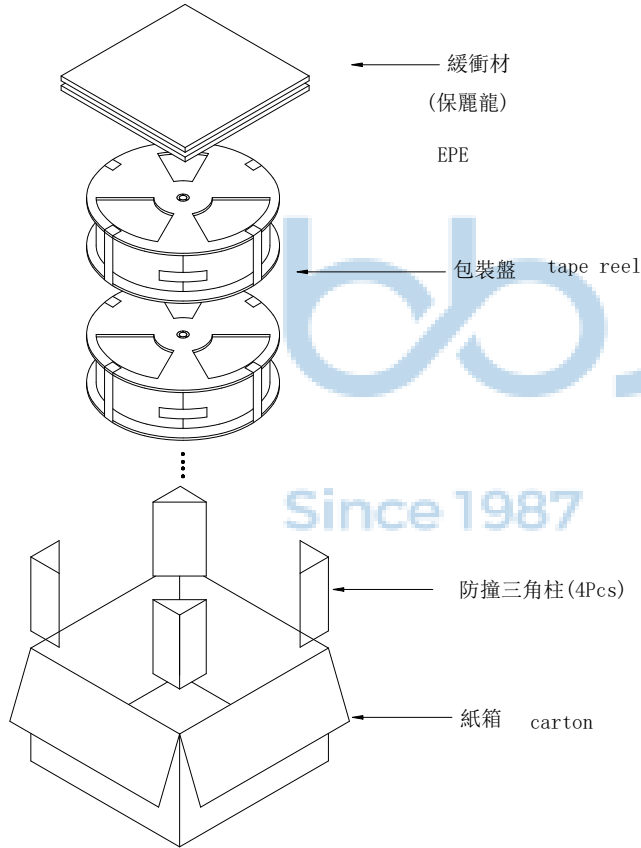


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PDWG.NO: 0366-2		深圳市步步精科技有限公司 NAME: TYPE-C 母座 24P 板上型 双壳 外壳四脚DIP 端子DIP+SMT L=8.65 外壳脚长1.2 带柱 不锈钢外壳 LCP黑胶 编带 APPD. JM_Zheng CHKD. LYX DR. GZY	
.X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13		X': $\pm 3'$.X': $\pm 2'$.XX': $\pm 1'$	
		PJ. NO.: SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/3	

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	GZY

at small positioning hole of the carrier tape side).
標籤黏貼處 (朝捲裝包材的小定位孔一側)

Location of label sticking (label)



NOTE:

1. 每捲包裝數量及每箱裝箱數量如左下表格。
Packing qty of each reel & carton as below table shown.
2. 以上膠帶覆蓋下包裝帶經包裝機冷封包裝
Use cover tape to cover and hot melt machine to seal up.
3. 將裝滿產品的卷盤放入紙箱並以膠帶封口
Put reels in the carton and use adhesive tape to seal up.



裝 容 量 (PACKING CAPACITY)		
PCS/REEL	REELS/CARTON	PCS/CARTON
700	10	7000

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PDWG.NO: 0366-2 APPD. JM_Zheng CHKD. LYX DR. GZY		NAME: TYPE-C 母座 24P 板上型 双壳 外壳四脚DIP 端子DIP+SMT L=8.65 外壳脚长1.2 带柱 不锈钢外壳 LCP黑胶 编带 .X: ±0.38 X': ±3" .XX: ±0.25 .X': ±2" .XXX: ±0.13 .XX': ±1"	PJ. NO.: SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 3/3